

HIGH DENSITY FOR ORGANIC CHIP CARRIERS

ABSTRACT

An organic integrated circuit chip carrier (14) for high density integrated circuit chip attach is disclosed. Contact pads (18) or microvias which provide electrical interconnections to external circuitry are located in a first array pattern, while plated through holes or through-vias are located in a second array pattern. This allows utilization of wiring channels within the chip carrier (14) in which signal wiring traces can be routed.

Fig 1.